

图书基本信息

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<<数字集成电路与嵌入式内核系统可测试性>>

内容概要

书中包括的索引使你能够根据自己的需要，直接阅读你所关注的内容。

主要内容包括：设计核心，关注嵌入核心和嵌入存储器；系统集成和超大规模集成电路的设计问题；AC扫描、正常速度扫描和嵌入式可测试性设计；内建、自测试、含内存BIST、逻辑BIST及扫描BIST；虚拟测试套接字和隔离测试

- 重用设计，包括重用和隔离测试；用VSIA和IEEE P1500标准处理测试问题。

书中穿插的整幅图解直接来自作者的教学材料。

通过为书中的第一部分列出流程图、工程图表和内容接要，使得读者能够更快更容易地学习和查找。本书是与设计和测试工作相关的工程师和管理员所备的资料书籍。

作者简介

Alfred L.Crouch从为美国空军修理气象设备开始其测试生涯。随后，他于肯塔基大学获得了电机工程学士和电机工程学硕士学位。他先后在德州仪器公司、数字装备公司和摩托罗拉公司供职，主要从事可测试性设计、测试自动化及计算机半自动测试。他总共申请了9个美国专利，是一名经验丰富的教员和会议主持者。

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